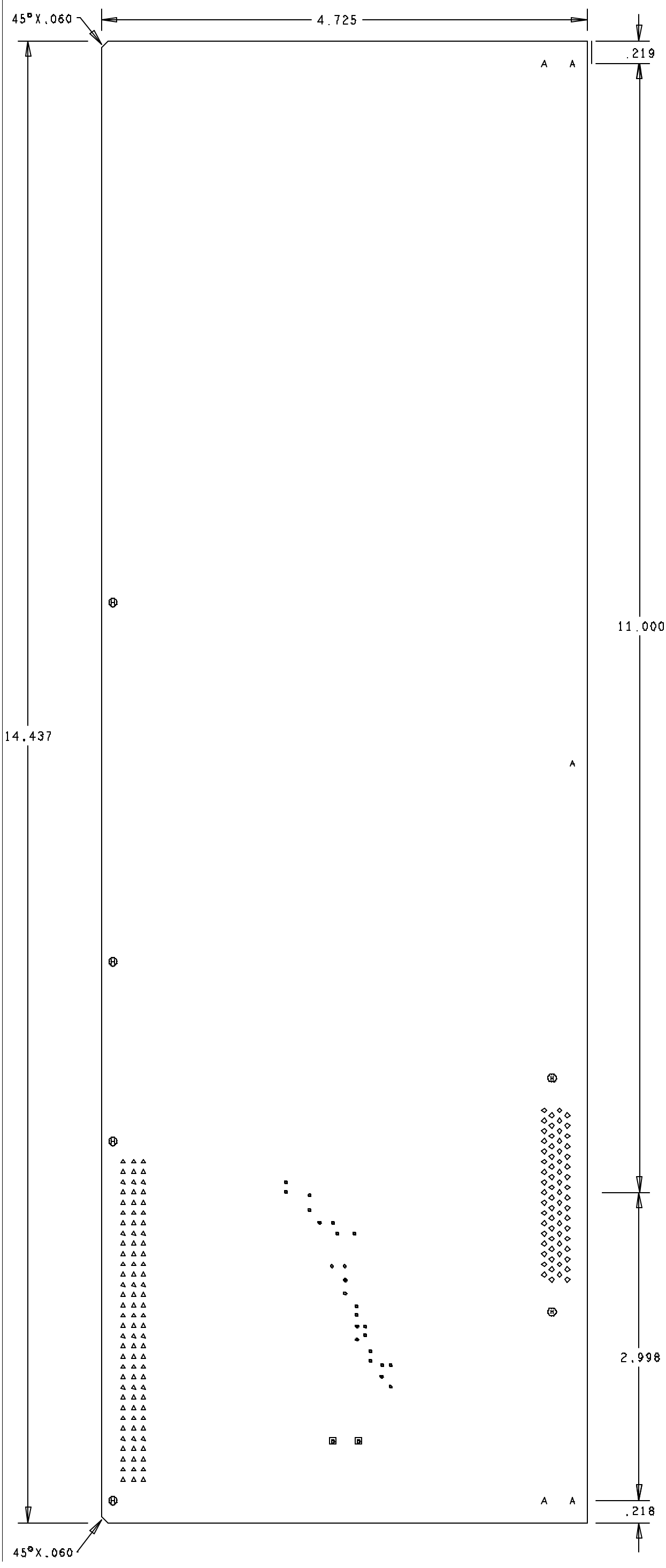

LAYER STACKING
COMPONENT
INT1
INT2
SOLDER

THRU-HOLES FOR 01PC176

/ FIGURE /	HOLESIZE /	QTY /
•	20-P	24
◇	29-P	68
△	35-P	96
▣	59-P	2
⊕	106-P	6
A	109-P	5

ANL/EL PCB FABRICATION NOTES

1.MATERIAL: PER REV.H MIL-P-13949 GFN GLASS EPOXY LAMINATE FINISHED BOARD THICKNESS .062 ± 005

2. DRILLING: UNLESS OTHERWISE SPECIFIED LOCATE HOLES PER DRILL ARTWORK ± 003 AND FINISHEDHOLE SIZES PER LEGEND ± 003

3.PLATING: ALL PLATING TO BE SMOOTH AND CONTINUOUS. COPPER PLATE THRU HOLES .001 MIN. WALL THICKNESS.SOLDER PLATE USING 60/40 TIN LEAD ± 5%.FINISHED THICKNESS .0003 MIN.

4.GOLDPLATE: NO GOLD REQUIRED ON THIS BOARD

5.FABRICATION: UNLESS OTHERWISE SPECIFIED,FAB.TO DIMENSIONS SHOWN ± .010. REMOVE ALL COPPER SHEAR MARKS. BEVEL ANY CONNECTOR TAB EDGES 1/64 X 30° BOTH SIDES

6.SOLDERMASK: APPLY SOLDER MASK TO 2 SIDES OF BOARD SOLDERMASK SHOULD NOT OVERLAP HOLE LAND AREAS.(SHINY)

7.NOMENCLATURE: SCREEN NOMENCLATURE TO COMPONENT SIDE OF BOARD USING 2 PART WHITE EPOXY INK.

ARGONNE NATIONAL LABORATORY

DIVISION ELECTRONICS

TITLE FAB.DWG.FOR MINOS MASTER AUXILIARY BOARD

SIZE	DOCUMENT NUMBER	ENG. BILL	REV
B	PCB-1382	HABERICHTER	*

DATE: 11/16/99 | EL CAD.#01PC176 | SHEET 1 OF 1